

Title (en)
PROCESS FOR MANUFACTURING A COMPONENT, ASSEMBLY, AND METHOD FOR ELECTRICALLY CONTACTING THE PRINTED CIRCUIT BOARD OF THE COMPONENT OR OF THE ASSEMBLY

Title (de)
VERFAHREN ZUR HERSTELLUNG EINES BAUTEILS, BAUGRUPPE UND VERFAHREN ZUR ELEKTRISCHEN KONTAKTIERUNG DER LEITERPLATTE DES BAUTEILS ODER DER BAUGRUPPE

Title (fr)
PROCÉDÉ DE FABRICATION D'UNE PIÈCE

Publication
EP 4154689 A2 20230329 (DE)

Application
EP 21728053 A 20210521

Priority

- DE 102020003088 A 20200522
- DE 102020003086 A 20200522
- DE 102020003087 A 20200522
- EP 2021063652 W 20210521

Abstract (en)
[origin: WO2021234146A2] The invention relates to a method for producing a component (1) which comprises a printed circuit board (2) and a plurality of electrical components (3) arranged thereon. According to the invention, the electrical components (3) are pre-fixed on the printed circuit board made of plastic by means of a fixing adhesive (9) and are subsequently fully cast with a UV adhesive (8).

IPC 8 full level
H05K 3/30 (2006.01); **B60R 13/00** (2006.01); **F21V 8/00** (2006.01); **G09F 13/04** (2006.01); **H01R 4/18** (2006.01); **H01R 12/58** (2011.01); **H05K 1/11** (2006.01); **H05K 1/18** (2006.01); **H05K 3/28** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP US)
B60R 13/005 (2013.01 - EP US); **H05K 1/0274** (2013.01 - US); **H05K 1/11** (2013.01 - EP); **H05K 1/18** (2013.01 - EP); **H05K 1/185** (2013.01 - US); **H05K 3/0058** (2013.01 - EP); **H05K 3/1216** (2013.01 - US); **H05K 3/284** (2013.01 - EP); **H05K 3/305** (2013.01 - EP US); **H05K 3/4015** (2013.01 - EP); **H05K 1/0203** (2013.01 - EP); **H05K 1/0265** (2013.01 - EP); **H05K 3/1216** (2013.01 - EP); **H05K 2201/0108** (2013.01 - EP US); **H05K 2201/0129** (2013.01 - US); **H05K 2201/09227** (2013.01 - EP); **H05K 2201/09236** (2013.01 - EP); **H05K 2201/09736** (2013.01 - EP US); **H05K 2201/10022** (2013.01 - EP US); **H05K 2201/10106** (2013.01 - EP US); **H05K 2201/10303** (2013.01 - EP US); **H05K 2201/2054** (2013.01 - EP); **H05K 2203/1476** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP)

Citation (search report)
See references of WO 2021234146A2

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
WO 2021234146 A2 20211125; **WO 2021234146 A3 20220331**; CN 115720728 A 20230228; EP 4154689 A2 20230329; US 2023209703 A1 20230629

DOCDB simple family (application)
EP 2021063652 W 20210521; CN 202180045649 A 20210521; EP 21728053 A 20210521; US 202117927204 A 20210521